Technical Data Sheet

Durite™ Resin D_PD-1623

Description

High purity cresol formaldehyde novolac resin

Application

D_PD-1623 is a low molecular weight resin used in semiconductor photoresist applications

Typical Properties

Property	Value	Unit
Appearance	Crushed solid	
Average Molecular Weight GPC	ca. 4500 – 5500	g/mol
Bulk Dissolution Rate 2.38% TMAH Developer, PAB 110°C/60 seconds	ca. 95 - 195	Å/sec
Free Cresol Content GC	1	%
Individual Trace Metal Content GFAA	max 500	ppb

Tests are made in accordance with the current Hexion Standard Test Method and are available upon request.

Storage

D_PD-1623 should be stored at 25°C in closed containers in a dry location. Over time the material may darken, could pick up moisture and potentially sinter.

Handling

This product has to be used and disposed of according to the indications given in its safety data sheet. Hexion Inc. solid products, including but not limited to powders and flake resin products, can be combustible and present a fire or explosion hazard under certain conditions (including, but not limited to when dusts are finely divided and suspended in air and/or allowed to accumulate on surfaces). Fine dust clouds may form explosive mixtures. The buyer must comply with all laws, regulations and standards applicable to the possession, handling and use of solid products by the buyer. Please consult US NFPA Standard 652 & 654, UK HSE Guidance HSG 103, or other national guidance on safe handling of combustible dusts.

Packaging

125kg drum

Note

As part of our quality assurance efforts, we ensure compliance with the indicated product parameters at the time of shipping. Phenolic resins are known to be subject to a process of change that depends on the storage and transportation conditions. Even when the material is stored at the conditions indicated above, the useful life must be individually verified by the user of our products.